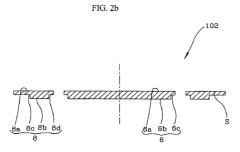
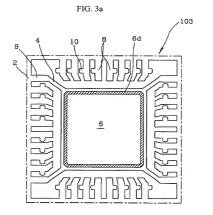


 $\label{eq:total_continuity} Title of Invention: \ Leadframe \ And Semiconductor Package Made Using The \ Leadframe \ Docket No.: \ AB-1134 \ US \ Inventors: \ Byung Hoon Ahn, et al. \\ Page $\underbrace{\textbf{2}}_{} \ of \ 7$$ 





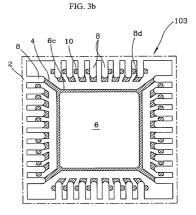
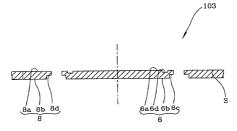


FIG. 3c





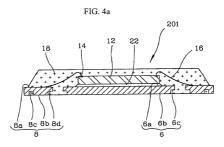


FIG. 4b

